

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	208	360/319.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:16
L2	9	("20020034055"   "20020075609"   "5739987"   "5894384"   "6078484"   "6223420"   "6317301"   "6765768"   "6785099").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/29 15:28
L3	2	"5855711".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:28
L4	24	("5085720"   "5130067"   "5254191"   "5370759"   "5387474"   "5456778"   "5470412"   "5474741").PN. OR ("5855711").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/29 15:35
L5	57	pcb and plug and laminating	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:40
L6	1	"20030110629".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:41
L7	0	HORNG near Gwo.inv.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:41
L8	2	HORNG near Gwo.inv.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:41
L9	0	("2004/0045656").URPN.	USPAT	OR	ON	2006/08/29 15:43
L10	522	chip near package near substrate	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:45
L11	0	chip near package near substrate and filling and firing and stacking and planariz\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:46

## EAST Search History

L12	0	chip near package near substrate and filling and stacking and planariz\$3	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:46
L13	0	chip near package near substrate and filling and stacking and planariz\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:46
L14	25	chip near package near substrate and planariz\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:47
L15	13	chip near package near substrate same method and "29"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:48
L16	140	chip near package near substrate same method and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:53
L17	11	chip near package near substrate same method and "257"/\$.ccls. and "29"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:54
L18	8	chip near package near substrate same method and "438"/\$.ccls. and "29"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:55

## EAST Search History

L19	0	chip near package near substrate same method and "156"/\$.ccls. and "29"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/29 15:55
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